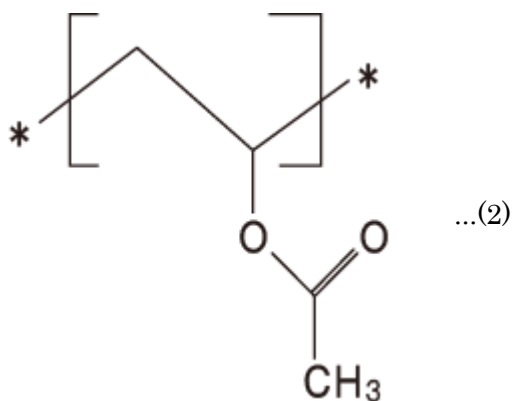
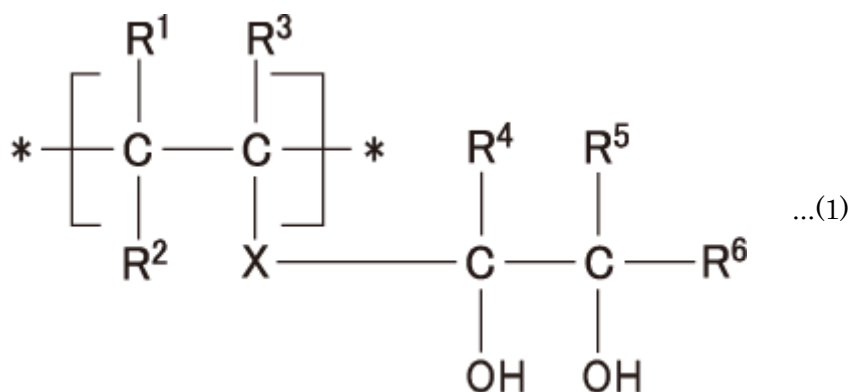


POLISHING COMPOSITION

ABSTRACT

A polishing composition is provided that can reduce minute defects and haze on a semiconductor wafer after polishing. A polishing composition contains: abrasives; a basic compound; and a vinyl alcohol-based resin having a 1,2-diol structural unit represented by general formula (1), the vinyl alcohol-based resin having a structural unit represented by general formula (2) in a molar concentration of 2 mol% or higher relative to the total of all structural units.



Here, each of R¹, R² and R³ independently indicates a hydrogen atom or an organic group, X indicates a single bond or a joining chain, and each of R⁴, R⁵ and R⁶ independently indicates hydrogen atom or an organic group.

[No Suitable Figure]